

74LVQ573 Low Voltage Octal Latch with 3-STATE Outputs

General Description

The LVQ573 is a high-speed octal latch with buffered common Latch Enable (LE) and buffered common Output Enable (\overline{OE}) inputs. The LVQ573 is functionally identical to the LVQ373 but with inputs and outputs on opposite sides of the package.

Features

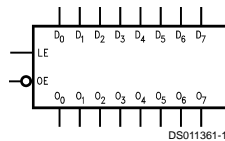
- Ideal for low power/low noise 3.3V applications
- Implements patented EMI reduction circuitry
- Available in SOIC JEDEC, SOIC EIAJ, and QSOP packages
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- Guaranteed incident wave switching into 75Ω
- 4 kV minimum ESD immunity

Ordering Code:

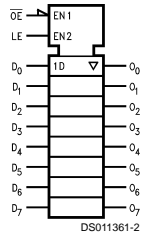
Order Number	Package Number	Package Description
74LVQ573SC	M20B	20-Lead (0.300" Wide) Molded Small Outline Package, SOIC, JEDEC
74LVQ573SJ	M20D	20-Lead Molded Shrink Small Outline Package, SOIC, EIAJ
74LVQ573QSC	MQA20	20-Lead (0.150" Wide) Molded Shrink Small Outline Package, SSOP, JEDEC

Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

Logic Symbols

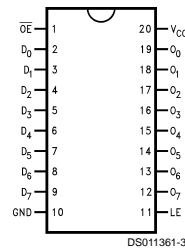


IEEE/IEC



Connection Diagram

Pin Assignment for SOIC and QSOP



Pin Descriptions

Pin Names	Description
D ₀ -D ₇	Data Inputs
LE	Latch Enable Input
\overline{OE}	3-STATE Output Enable Input
O ₀ -O ₇	3-STATE Latch Outputs

Truth Table

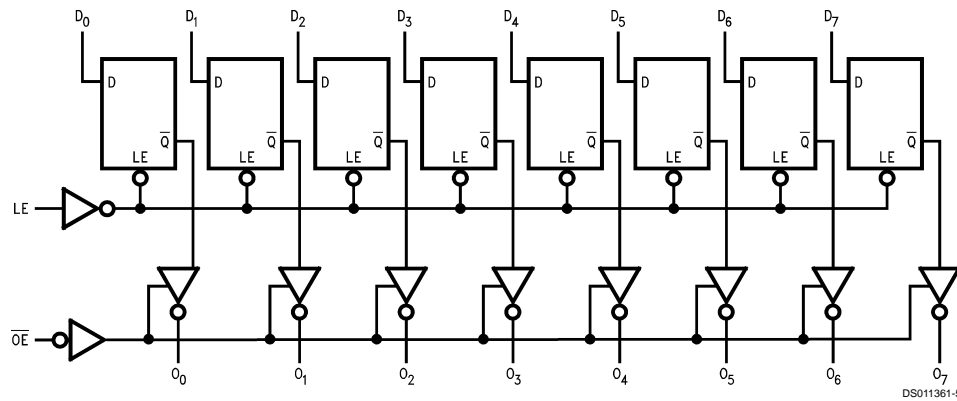
Inputs			Outputs
\overline{OE}	LE	D	O_n
L	H	H	H
L	H	L	L
L	L	X	O_0
H	X	X	Z

H = HIGH Voltage
 L = LOW Voltage
 Z = High Impedance
 X = Immaterial
 O_0 = Previous O_0 before HIGH-to-LOW transition of Latch Enable

Functional Description

The LVQ573 contains eight D-type latches with 3-STATE output buffers. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D-type input changes. When LE is LOW the latches store the information that was present on the D-type inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE buffers are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the buffers are enabled. When \overline{OE} is HIGH the buffers are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings (Note 1)

Supply Voltage (V_{CC})	-0.5V to +7.0V
DC Input Diode Current (I_{IK})	
$V_I = -0.5V$	-20 mA
$V_I = V_{CC} + 0.5V$	+20 mA
DC Input Voltage (V_I)	-0.5V to $V_{CC} + 0.5V$
DC Output Diode Current (I_{OK})	
$V_O = -0.5V$	-20 mA
$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage (V_O)	-0.5V to $V_{CC} + 0.5V$
DC Output Source or Sink Current (I_O)	±50 mA
DC V_{CC} or Ground Current (I_{CC} or I_{GND})	±400 mA
Storage Temperature (T_{STG})	-65°C to +150°C
DC Latch-Up Source or Sink Current	±300 mA

Recommended Operating Conditions (Note 2)

Supply Voltage (V_{CC})	2.0V to 3.6V
Input Voltage (V_I)	0V to V_{CC}
Output Voltage (V_O)	0V to V_{CC}
Operating Temperature (T_A)	-40°C to +85°C
Minimum Input Edge Rate ($\Delta V/\Delta t$)	
V_{IN} from 0.8V to 2.0V	
V_{CC} @ 3.0V	125 mV/ns

Note 1: The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 2: Unused inputs must be held HIGH or LOW. They may not float.

DC Electrical Characteristics

Symbol	Parameter	V_{CC} (V)	$T_A = +25^\circ C$		$T_A = -40^\circ C$ to $+85^\circ C$	Units	Conditions
			Typ	Guaranteed Limits			
V_{IH}	Minimum High Level Input Voltage	3.0	1.5	2.0	2.0	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$
V_{IL}	Maximum Low Level Input Voltage	3.0	1.5	0.8	0.8	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$
V_{OH}	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	$I_{OUT} = -50 \mu A$
		3.0		2.58	2.48	V	$V_{IN} = V_{IL}$ or V_{IH} (Note 3) $I_{OH} = -12 \text{ mA}$
V_{OL}	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	$I_{OUT} = 50 \mu A$
		3.0		0.36	0.44	V	$V_{IN} = V_{IL}$ or V_{IH} (Note 3) $I_{OL} = 12 \text{ mA}$
I_{IN}	Maximum Input Leakage Current	3.6		±0.1	±1.0	µA	$V_I = V_{CC}, GND$
I_{OLD}	Minimum Dynamic Output Current (Note 4)	3.6			36	mA	$V_{OLD} = 0.8 V_{Max}$ (Note 5)
I_{OHD}		3.6			-25	mA	$V_{OHD} = 2.0V V_{Min}$ (Note 5)
I_{CC}	Maximum Quiescent Supply Current	3.6		4.0	40.0	µA	$V_{IN} = V_{CC}$ or GND
I_{OZ}	3-STATE Leakage Current	3.6		±0.25	±2.5	µA	$V_I (\overline{OE}) = V_{IL}, V_{IH}$ $V_I = V_{CC}, GND$ $V_O = V_{CC}, GND$
V_{OLP}	Quiet Output Maximum Dynamic V_{OL}	3.3	0.4	0.8		V	(Notes 6, 7)
V_{OLV}	Quiet Output Minimum Dynamic V_{OL}	3.3	-0.4	-0.8		V	(Notes 6, 7)
V_{IHD}	Maximum High Level Dynamic Input Voltage	3.3	1.6	2.0		V	(Notes 6, 8)
V_{ILD}	Maximum Low Level Dynamic Input Voltage	3.3	1.6	0.8		V	(Notes 6, 8)

Note 3: All outputs loaded; thresholds on input associated with output under test.

Note 4: Maximum test duration 2.0 ms, one output loaded at a time.

Note 5: Incident wave switching on transmission lines with impedances as low as 75Ω for commercial temperature range is guaranteed for.

Note 6: Worst case package.

Note 7: Max number of outputs defined as (n). Data inputs are driven 0V to 3.3V; one output at GND.

Note 8: Max number of Data Inputs (n) switching. (n - 1) inputs switching 0V to 3.3V. Input-under-test switching: 3.3V to threshold (V_{ILD}), 0V to threshold (V_{IHD}), f = 1 MHz.

AC Electrical Characteristics

Symbol	Parameter	V _{CC} (V)	T _A = +25°C C _L = 50 pF			T _A = -40°C to +85°C C _L = 50 pF		Units
			Min	Typ	Max	Min	Max	
t _{PHL}	Propagation Delay	2.7	2.5	10.2	14.8	2.5	16.0	ns
t _{PLH}	D _n to O _n	3.3 ±0.3	2.5	8.5	10.5	2.5	11.0	
t _{PLH}	Propagation Delay	2.7	2.5	10.2	16.9	2.5	18.0	ns
t _{PHL}	LE to O _n	3.3 ±0.3	2.5	8.5	12.0	2.5	12.5	
t _{PZL}	Output Enable Time	2.7	2.5	10.2	18.3	2.5	19.0	ns
t _{PZH}	Output Disable Time	2.7	1.0	10.8	20.4	1.0	21.0	
t _{PHZ}	Output Disable Time	2.7	1.0	10.8	20.4	1.0	21.0	ns
t _{PLZ}		3.3 ±0.3	1.0	9.0	14.5	1.0	15.0	
t _{OSHL}	Output to Output Skew (Note 9)	2.7		1.0	1.5		1.5	ns
t _{OSLH}	D _n to O _n	3.3 ±0.3		1.0	1.5		1.5	

Note 9: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH to LOW (t_{OSHL}) or LOW to HIGH (t_{OSLH}). Parameter guaranteed by design.

AC Operating Requirements

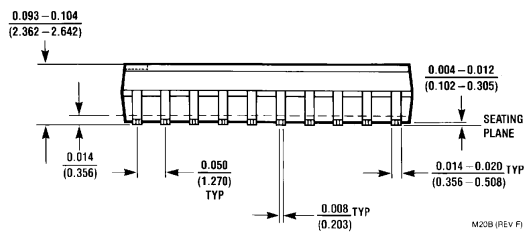
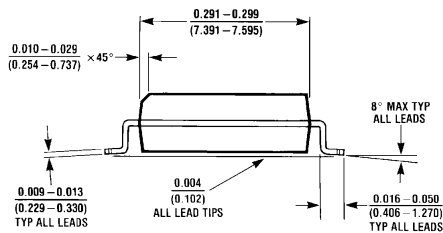
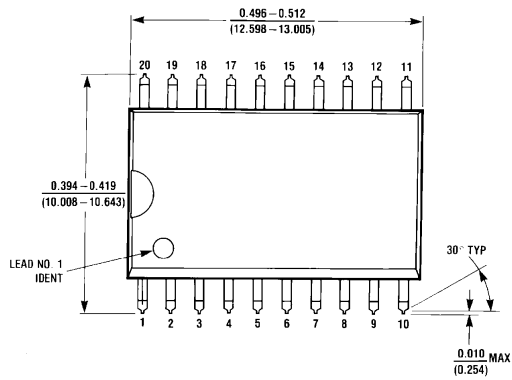
Symbol	Parameter	V _{CC} (V)	T _A = +25°C C _L = 50 pF		T _A = -40°C to +85°C C _L = 50 pF		Units
			Typ	Guaranteed Minimum	Typ	Guaranteed Minimum	
t _S	Setup Time, HIGH or LOW	2.7	0	4.0	4.5	ns	
	D _n to LE	3.3 ±0.3	0	3.0	3.0		
t _H	Hold Time, HIGH or LOW	2.7	0	1.5	1.5	ns	
	D _n to LE	3.3 ±0.3	0	1.5	1.5		
t _W	LE Pulse Width, HIGH	2.7	2.4	5.0	6.0	ns	
		3.3 ±0.3	2.0	4.0	4.0		

Capacitance

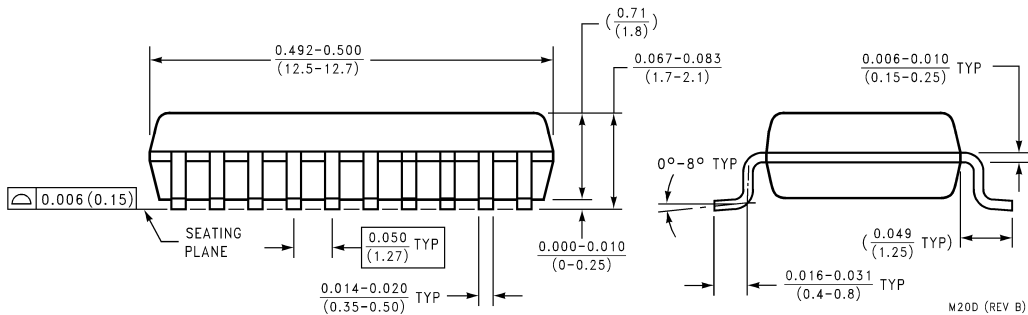
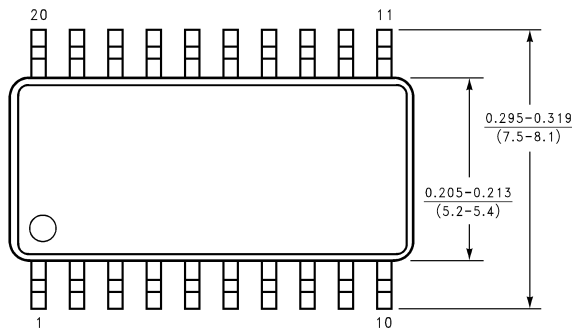
Symbol	Parameter	Typ	Units	Conditions
C _{IN}	Input Capacitance	4.5	pF	V _{CC} = Open
C _{PD} (Note 10)	Power Dissipation Capacitance	37	pF	V _{CC} = 3.3V

Note 10: C_{PD} is measured at 10 MHz.

Physical Dimensions inches (millimeters) unless otherwise noted

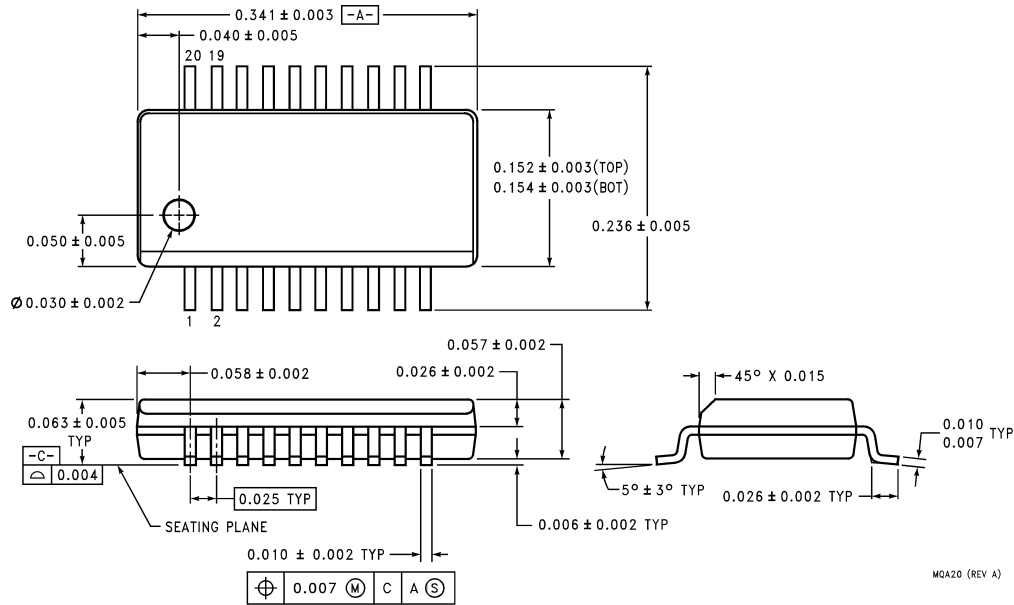


**20-Lead (0.300" Wide) Molded Small Outline Package, SOIC, JEDEC
Package Number M20B**



**20-Lead Molded Shrink Small Outline Package, SOIC, EIAJ
Package Number M20D**

Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



**20-Lead (0.150" Wide) Molded Shrink Small Outline Package, SSOP, JEDEC
(also known as QSOP)
Package Number MQA20**

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